

# NTMFD4C20N

## MOSFET – Power, Dual, N-Channel, SO8FL

30 V, High Side 18 A / Low Side 27 A

### Features

- Co-Packaged Power Stage Solution to Minimize Board Space
- Minimized Parasitic Inductances
- Optimized Devices to Reduce Power Losses
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### Applications

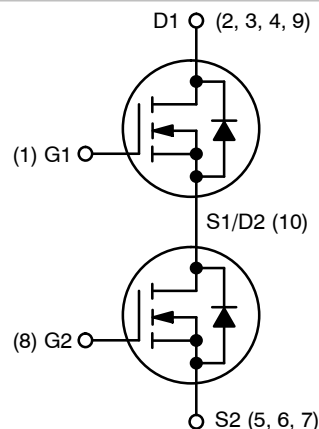
- DC-DC Converters
- System Voltage Rails
- Point of Load



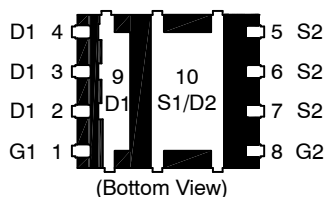
ON Semiconductor®

[www.onsemi.com](http://www.onsemi.com)

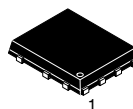
V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
Q1 Top FET 30 V	7.3 mΩ @ 10 V	18 A
	10.8 mΩ @ 4.5 V	
Q2 Bottom FET 30 V	3.4 mΩ @ 10 V	27 A
	5.2 mΩ @ 4.5 V	



### PIN CONNECTIONS



### MARKING DIAGRAM



DFN8  
CASE 506BX



4C20N = Specific Device Code  
 A = Assembly Location  
 Y = Year  
 W = Work Week  
 ZZ = Lot Traceability

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

# NTMFD4C20N

## MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise stated)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage	Q1	Q1	$V_{DSS}$	30	V
Drain-to-Source Voltage	Q2				
Gate-to-Source Voltage	Q1	Q1	$V_{GS}$	$\pm 20$	V
Gate-to-Source Voltage	Q2				
Continuous Drain Current $R_{\theta JA}$ (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	Q1	$I_D$	12
		$T_A = 85^\circ\text{C}$			8.6
		$T_A = 25^\circ\text{C}$	Q2	$I_D$	18
		$T_A = 85^\circ\text{C}$			13
Power Dissipation $R_{\theta JA}$ (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	Q1	$P_D$	1.88
			Q2		1.97
Continuous Drain Current $R_{\theta JA} \leq 10$ s (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	Q1	$I_D$	18.2
					$T_A = 85^\circ\text{C}$
		$T_A = 25^\circ\text{C}$	27.4		
		$T_A = 85^\circ\text{C}$	19.8		
Power Dissipation $R_{\theta JA} \leq 10$ s (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	Q1	$P_D$	4.37
			Q2		4.6
Continuous Drain Current $R_{\theta JA}$ (Note 2)	Steady State	$T_A = 25^\circ\text{C}$	Q1	$I_D$	9.1
					$T_A = 85^\circ\text{C}$
		$T_A = 25^\circ\text{C}$	13.7		
		$T_A = 85^\circ\text{C}$	9.9		
Power Dissipation $R_{\theta JA}$ (Note 2)	Steady State	$T_A = 25^\circ\text{C}$	Q1	$P_D$	1.09
			Q2		1.15
Pulsed Drain Current	Steady State	$T_A = 25^\circ\text{C}$ $t_p = 10 \mu\text{s}$	Q1	$I_{DM}$	55
			Q2		82
Operating Junction and Storage Temperature			Q1	$T_J, T_{STG}$	-55 to +150
			Q2		
Source Current (Body Diode)			Q1	$I_S$	4.0
			Q2		4.2
Drain to Source DV/DT				$dV/dt$	6
Single Pulse Drain-to-Source Avalanche Energy ( $T_J = 25^\circ\text{C}$ , $V_{DD} = 50$ V, $V_{GS} = 10$ V, $L = 0.1$ mH, $R_G = 25 \Omega$ )	$I_L = 18 A_{pk}$		Q1	EAS	16
	$I_L = 29 A_{pk}$		Q2	EAS	42
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)				$T_L$	260

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- Surface-mounted on FR4 board using 1 sq-in pad, 2 oz Cu.
- Surface-mounted on FR4 board using the minimum recommended pad size of 100 mm<sup>2</sup>.

# NTMFD4C20N

## THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	FET	Symbol	Value	Unit
Junction-to-Ambient – Steady State (Note 3)	Q1	$R_{\theta JA}$	66.5	°C/W
	Q2		63.3	
Junction-to-Ambient – Steady State (Note 4)	Q1	$R_{\theta JA}$	114.3	
	Q2		108.7	
Junction-to-Ambient – ( $t \leq 10$ s) (Note 3)	Q1	$R_{\theta JA}$	28.6	
	Q2		27.2	
Junction-to-Case – (Drain)	Q1	$R_{\theta JC}$	5.4	
	Q2		3.7	

3. Surface-mounted on FR4 board using 1 sq-in pad, 2 oz Cu.

4. Surface-mounted on FR4 board using the minimum recommended pad size of 100 mm<sup>2</sup>.

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	FET	Symbol	Test Condition	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	Q1	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	30			V
	Q2		$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$	30			
Drain-to-Source Breakdown Voltage Temperature Coefficient	Q1	$V_{(BR)DSS}/T_J$			14.5		mV/°C
	Q2				12		
Zero Gate Voltage Drain Current	Q1	$I_{DSS}$	$V_{GS} = 0\text{ V}, V_{DS} = 24\text{ V}$	$T_J = 25^\circ\text{C}$		1	$\mu\text{A}$
				$T_J = 125^\circ\text{C}$		10	
	Q2		$V_{GS} = 0\text{ V}, V_{DS} = 24\text{ V}$	$T_J = 25^\circ\text{C}$		10	
Gate-to-Source Leakage Current	Q1	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA
	Q2					$\pm 100$	

### ON CHARACTERISTICS (Note 5)

Gate Threshold Voltage	Q1	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\ \mu\text{A}$	1.3		2.1	V
	Q2			1.3		2.1	
Negative Threshold Temperature Coefficient	Q1	$V_{GS(TH)}/T_J$			4.7		mV/°C
	Q2				5.1		
Drain-to-Source On Resistance	Q1	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 10\text{ A}$		5.8	7.3	m $\Omega$
			$V_{GS} = 4.5\text{ V}, I_D = 10\text{ A}$		8.7	10.8	
	Q2		$V_{GS} = 10\text{ V}, I_D = 20\text{ A}$		2.7	3.4	
			$V_{GS} = 4.5\text{ V}, I_D = 20\text{ A}$		4.0	5.2	
Forward Transconductance	Q1	$g_{FS}$	$V_{DS} = 1.5\text{ V}, I_D = 10\text{ A}$		43		S
	Q2				68		

5. Pulse Test: pulse width  $\leq 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$ .

6. Switching characteristics are independent of operating junction temperatures.

# NTMFD4C20N

## ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	FET	Symbol	Test Condition	Min	Typ	Max	Unit		
<b>CHARGES, CAPACITANCES &amp; GATE RESISTANCE</b>									
Input Capacitance	Q1	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 15 V		970		pF		
	Q2				1950				
Output Capacitance	Q1	C <sub>OSS</sub>			430				
	Q2				990				
Reverse Capacitance	Q1	C <sub>RSS</sub>			125				
	Q2				50				
Total Gate Charge	Q1	Q <sub>G(TOT)</sub>		V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 15 V; I <sub>D</sub> = 10 A		9.3			nC
	Q2					13			
Threshold Gate Charge	Q1	Q <sub>G(TH)</sub>			1.6				
	Q2				3.3				
Gate-to-Source Charge	Q1	Q <sub>GS</sub>			3.3				
	Q2				6.0				
Gate-to-Drain Charge	Q1	Q <sub>GD</sub>			4.2				
	Q2				3.0				
Total Gate Charge	Q1	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 15 V; I <sub>D</sub> = 10 A		19		nC		
	Q2				29				

### SWITCHING CHARACTERISTICS (Note 6)

Turn-On Delay Time	Q1	t <sub>d(ON)</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A, R <sub>G</sub> = 3.0 Ω		9.0		ns
	Q2				11		
Rise Time	Q1	t <sub>r</sub>			33		
	Q2				32		
Turn-Off Delay Time	Q1	t <sub>d(OFF)</sub>			15		
	Q2				20		
Fall Time	Q1	t <sub>f</sub>			5.0		
	Q2				5.0		

### SWITCHING CHARACTERISTICS (Note 6)

Turn-On Delay Time	Q1	t <sub>d(ON)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A, R <sub>G</sub> = 3.0 Ω		6.0		ns
	Q2				8.0		
Rise Time	Q1	t <sub>r</sub>			26		
	Q2				26		
Turn-Off Delay Time	Q1	t <sub>d(OFF)</sub>			18		
	Q2				25		
Fall Time	Q1	t <sub>f</sub>			4.0		
	Q2				4.0		

### DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Voltage	Q1	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 3 A	T <sub>J</sub> = 25°C	0.75	1.0	V
				T <sub>J</sub> = 125°C	0.62		
	Q2		V <sub>GS</sub> = 0 V, I <sub>S</sub> = 3 A	T <sub>J</sub> = 25°C	0.45	0.70	
				T <sub>J</sub> = 125°C	0.37		

5. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.

6. Switching characteristics are independent of operating junction temperatures.

# NTMFD4C20N

## ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	FET	Symbol	Test Condition	Min	Typ	Max	Unit
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### DRAIN-SOURCE DIODE CHARACTERISTICS

Parameter	FET	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Recovery Time	Q1	t <sub>RR</sub>	V <sub>GS</sub> = 0 V, d <sub>IS</sub> /d <sub>t</sub> = 100 A/μs, I <sub>S</sub> = 30 A		23		ns
	Q2				38		
Charge Time	Q1	t <sub>a</sub>			11.6		
	Q2				18.6		
Discharge Time	Q1	t <sub>b</sub>			11.4		
	Q2				19.4		
Reverse Recovery Charge	Q1	Q <sub>RR</sub>			10		nC
	Q2				25		

### PACKAGE PARASITIC VALUES

Parameter	FET	Symbol	Test Condition	Min	Typ	Max	Unit	
Source Inductance	Q1	L <sub>S</sub>	T <sub>A</sub> = 25°C		0.38		nH	
	Q2				0.65			
Drain Inductance	Q1	L <sub>D</sub>			0.054		nH	
	Q2				0.007			
Gate Inductance	Q1	L <sub>G</sub>			1.5		nH	
	Q2				1.5			
Gate Resistance	Q1	R <sub>G</sub>			0.3	1.0	2.0	Ω
	Q2				0.3	1.0	2.0	

5. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.

6. Switching characteristics are independent of operating junction temperatures.

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NTMFD4C20NT1G	DFN8 (Pb-Free)	1500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NTMFD4C20N

## TYPICAL CHARACTERISTICS – Q1

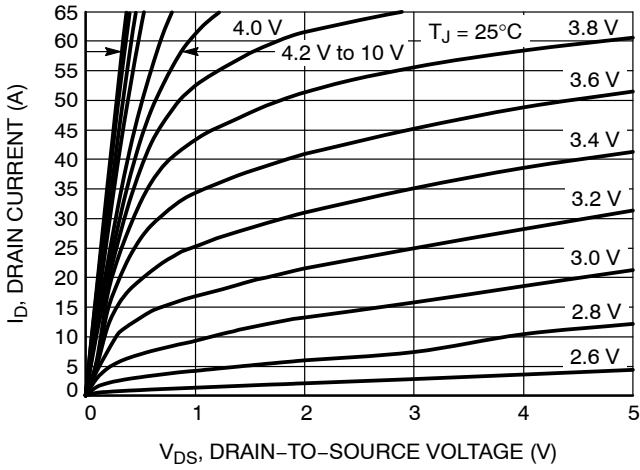


Figure 1. On-Region Characteristics

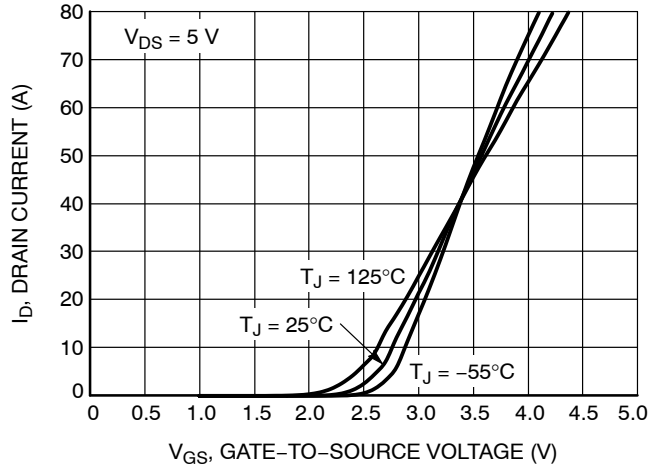


Figure 2. Transfer Characteristics

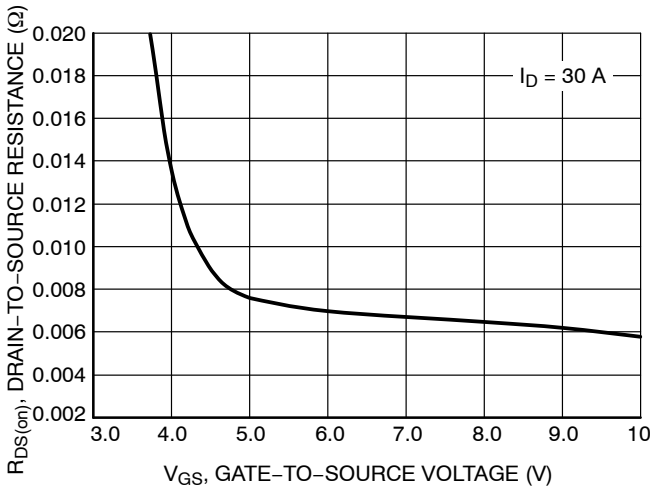


Figure 3. On-Resistance vs.  $V_{GS}$

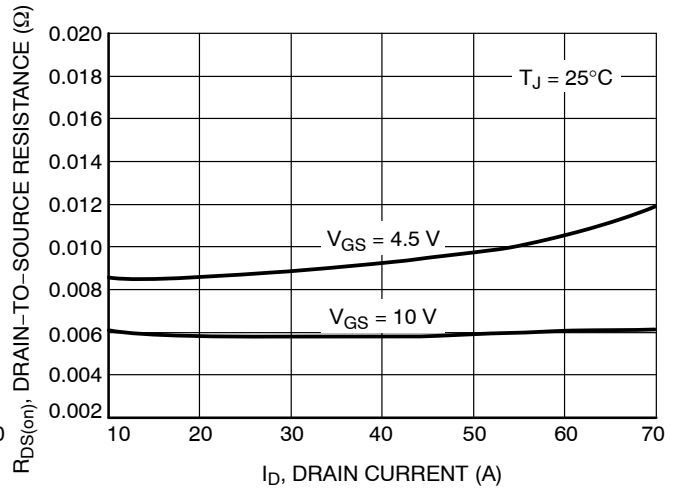


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

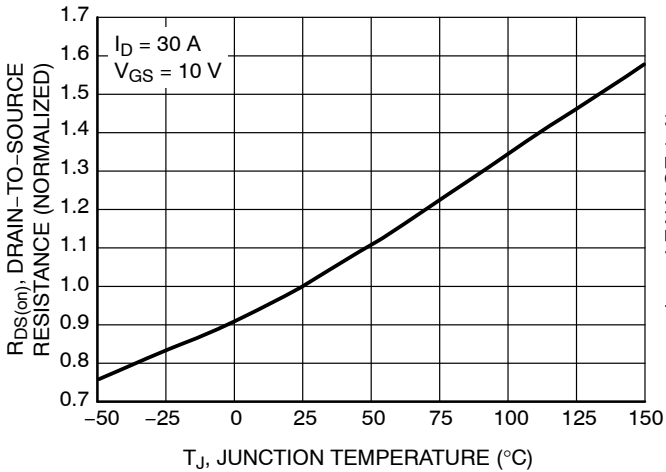


Figure 5. On-Resistance Variation with Temperature

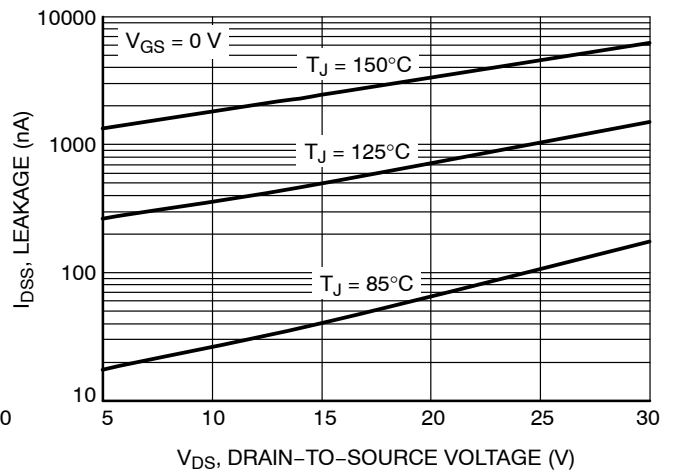


Figure 6. Drain-to-Source Leakage Current vs. Voltage

# NTMFD4C20N

## TYPICAL CHARACTERISTICS – Q1

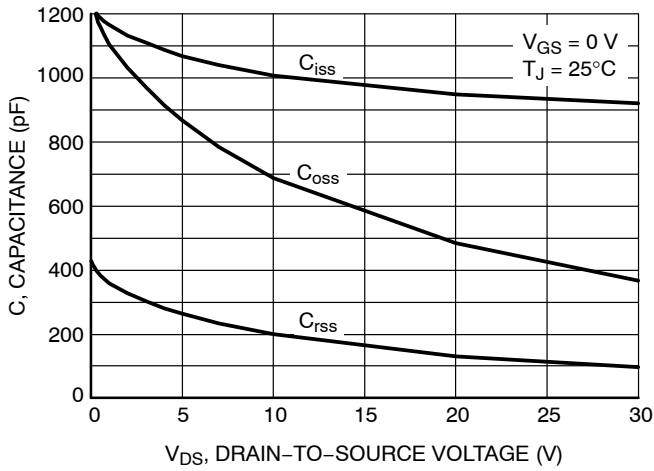


Figure 7. Capacitance Variation

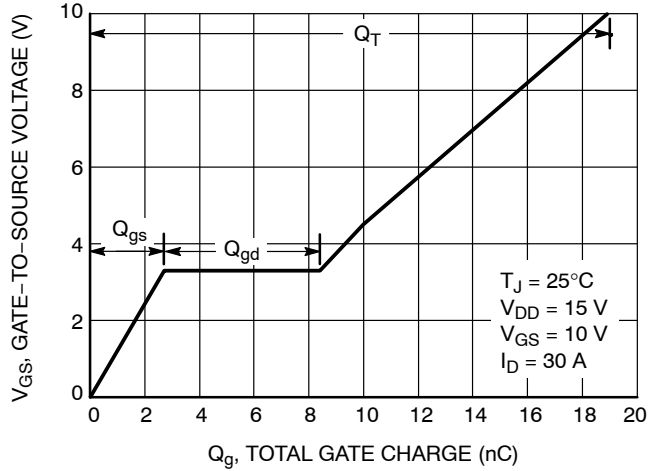


Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

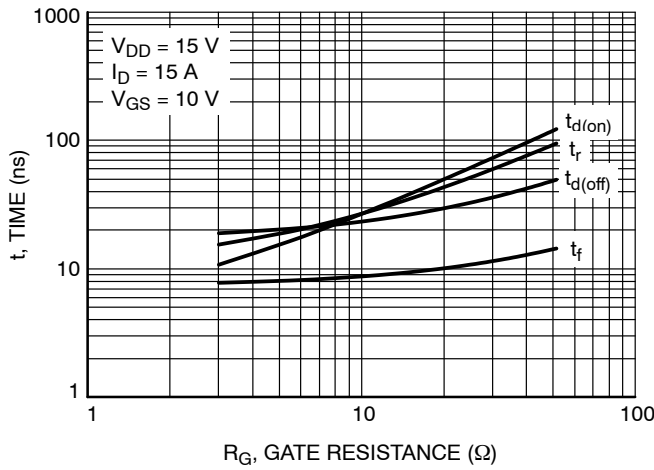


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

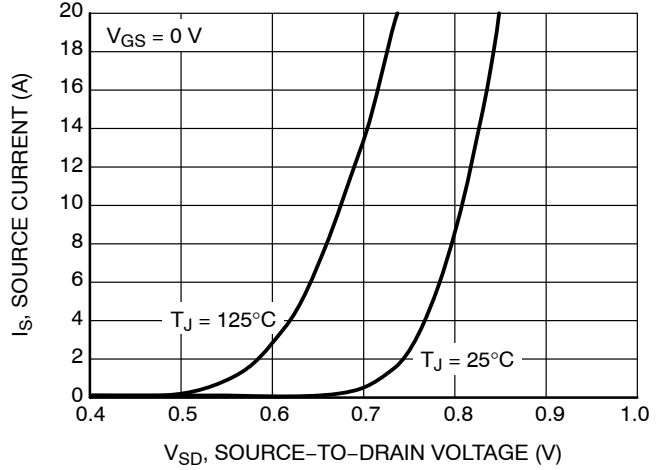


Figure 10. Diode Forward Voltage vs. Current

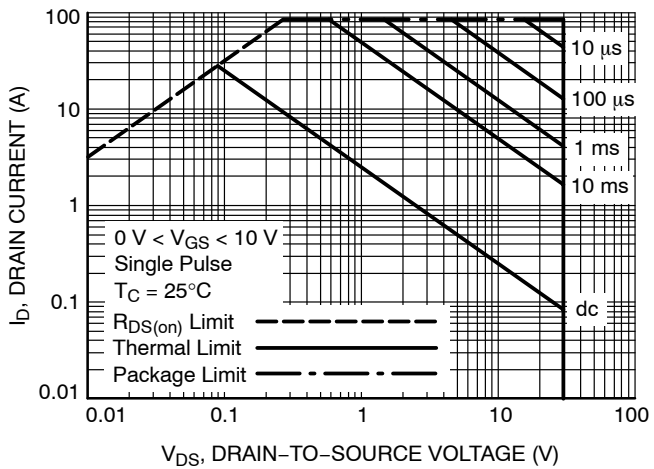


Figure 11. Maximum Rated Forward Biased Safe Operating Area

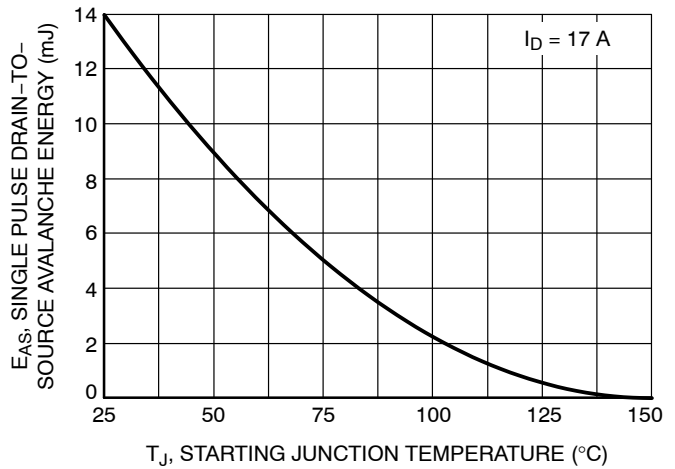


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

# NTMFD4C20N

## TYPICAL CHARACTERISTICS – Q1

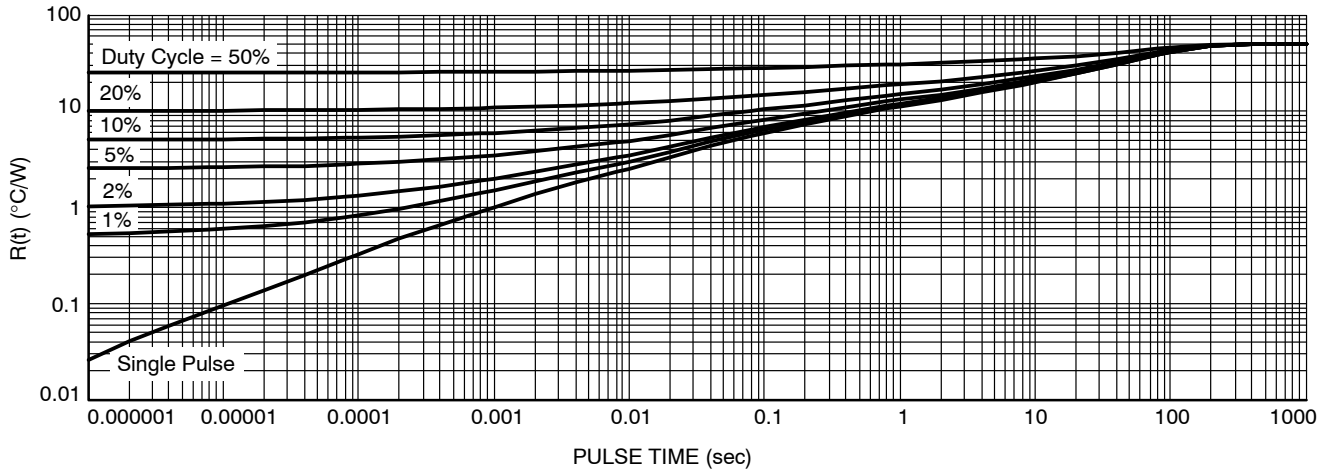


Figure 13. Thermal Response

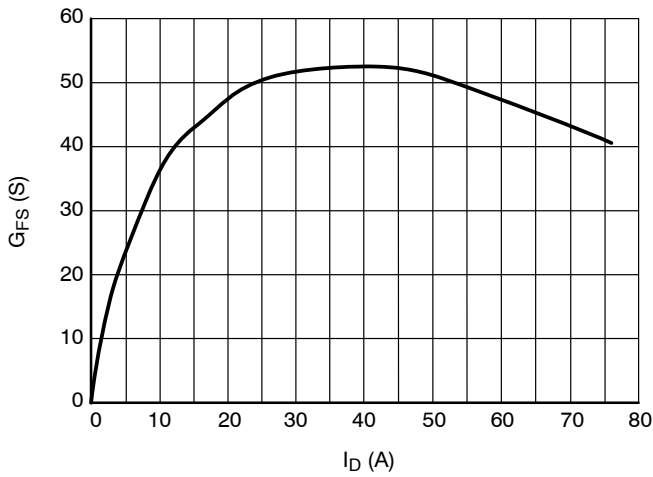


Figure 14.  $G_{FS}$  vs.  $I_D$

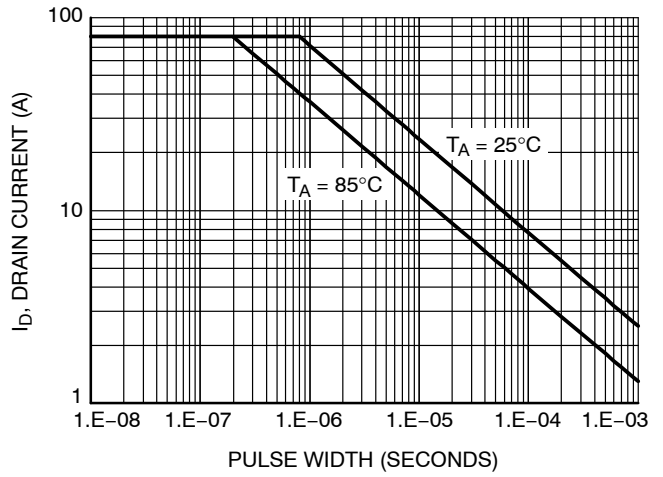


Figure 15. Avalanche Characteristics



# NTMFD4C20N

## TYPICAL CHARACTERISTICS – Q2

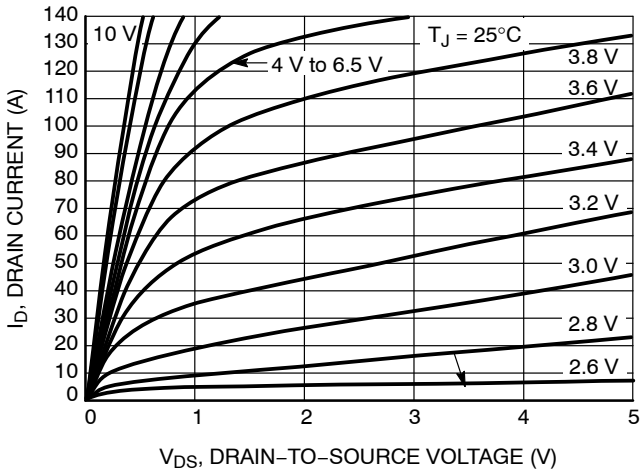


Figure 16. On-Region Characteristics

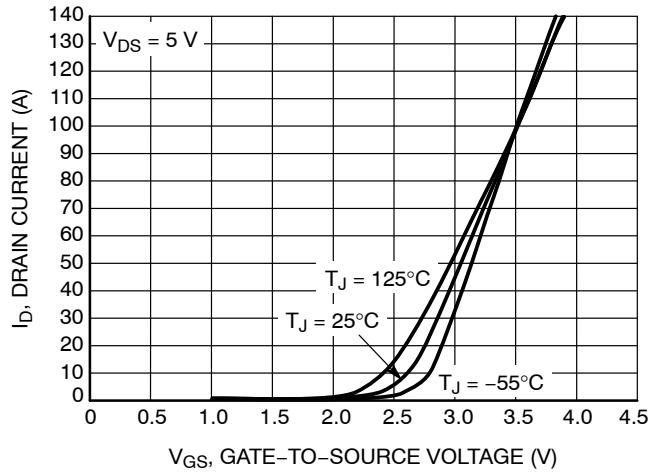


Figure 17. Transfer Characteristics

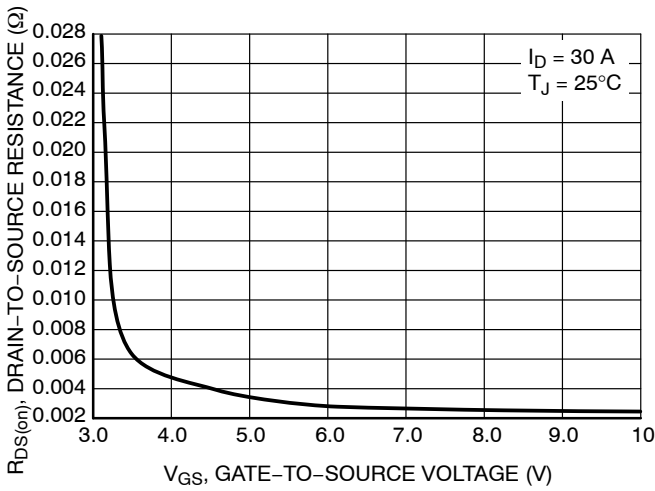


Figure 18. On-Resistance vs.  $V_{GS}$

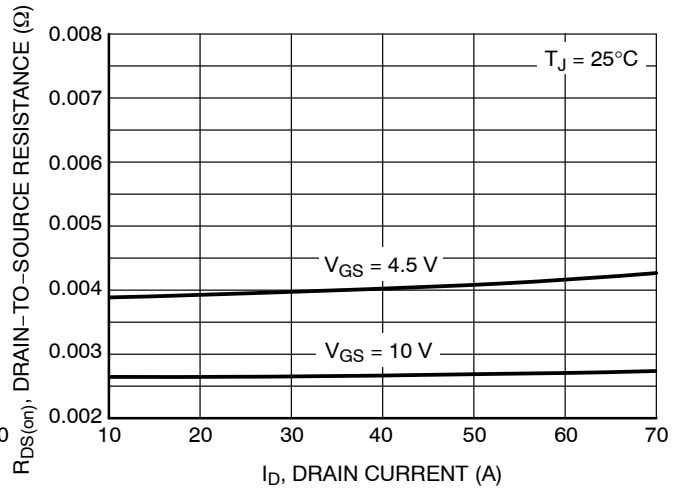


Figure 19. On-Resistance vs. Drain Current and Gate Voltage

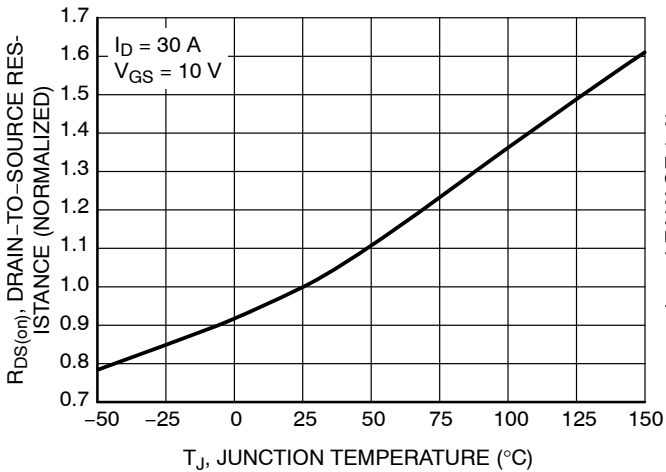


Figure 20. On-Resistance Variation with Temperature

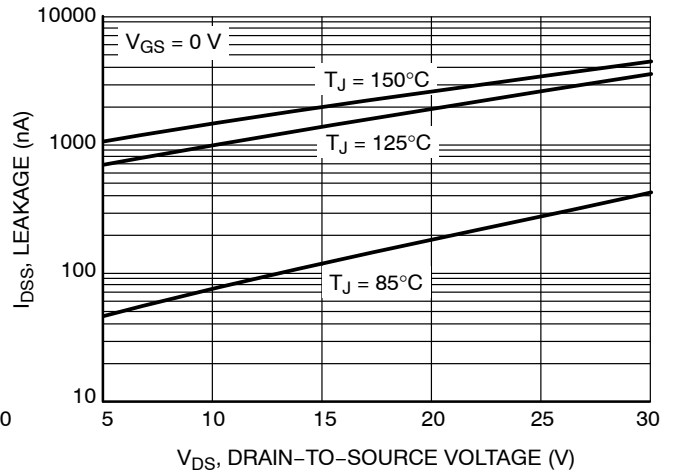


Figure 21. Drain-to-Source Leakage Current vs. Voltage

# NTMFD4C20N

## TYPICAL CHARACTERISTICS – Q2

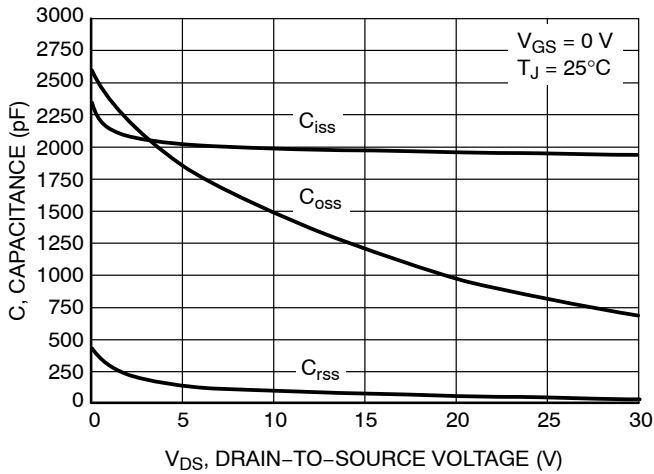


Figure 22. Capacitance Variation

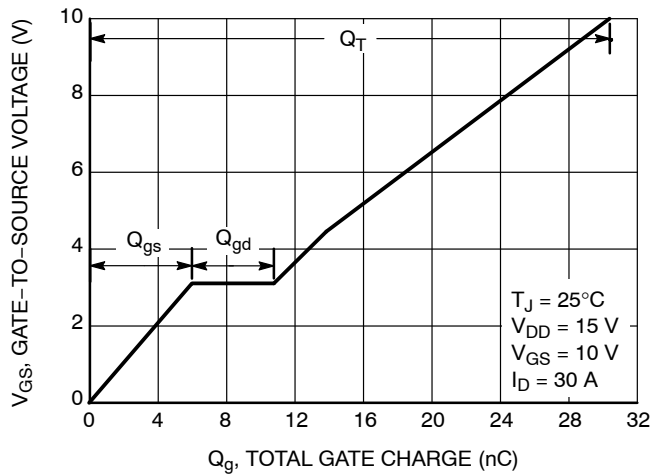


Figure 23. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

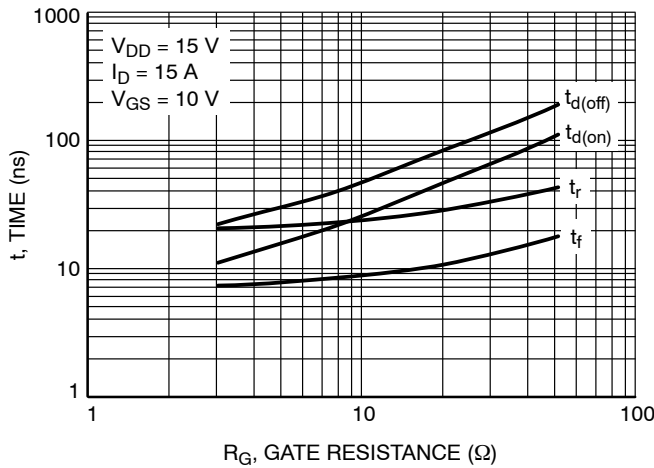


Figure 24. Resistive Switching Time Variation vs. Gate Resistance

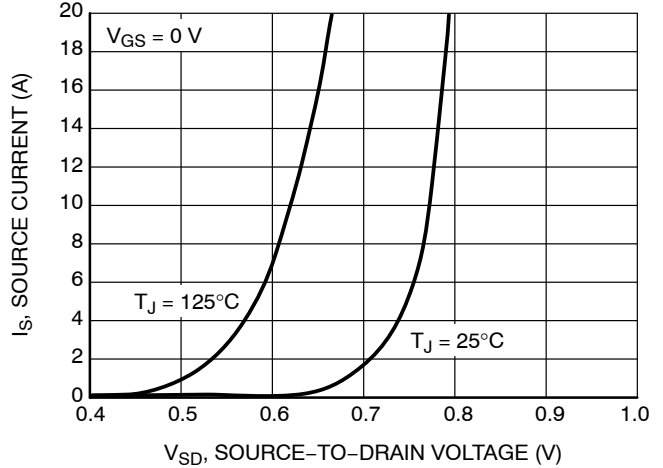


Figure 25. Diode Forward Voltage vs. Current

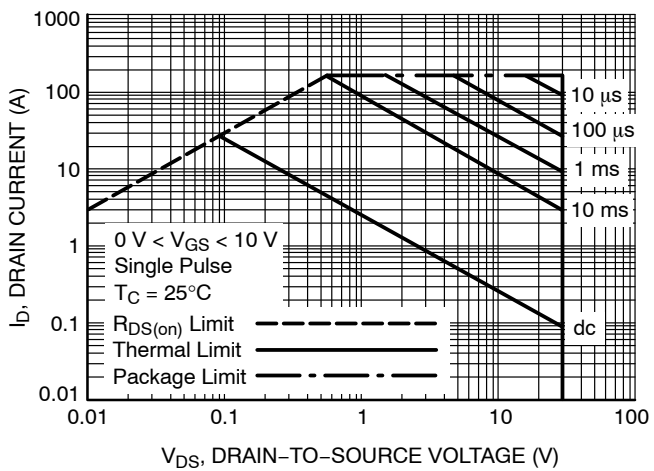


Figure 26. Maximum Rated Forward Biased Safe Operating Area

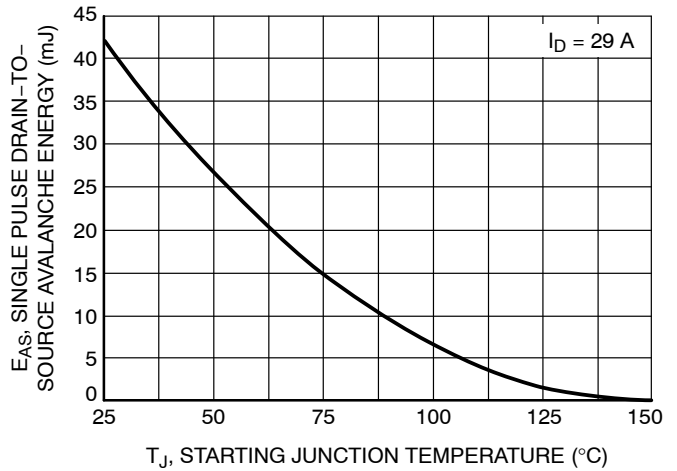


Figure 27. Maximum Avalanche Energy vs. Starting Junction Temperature

# NTMFD4C20N

## TYPICAL CHARACTERISTICS – Q2

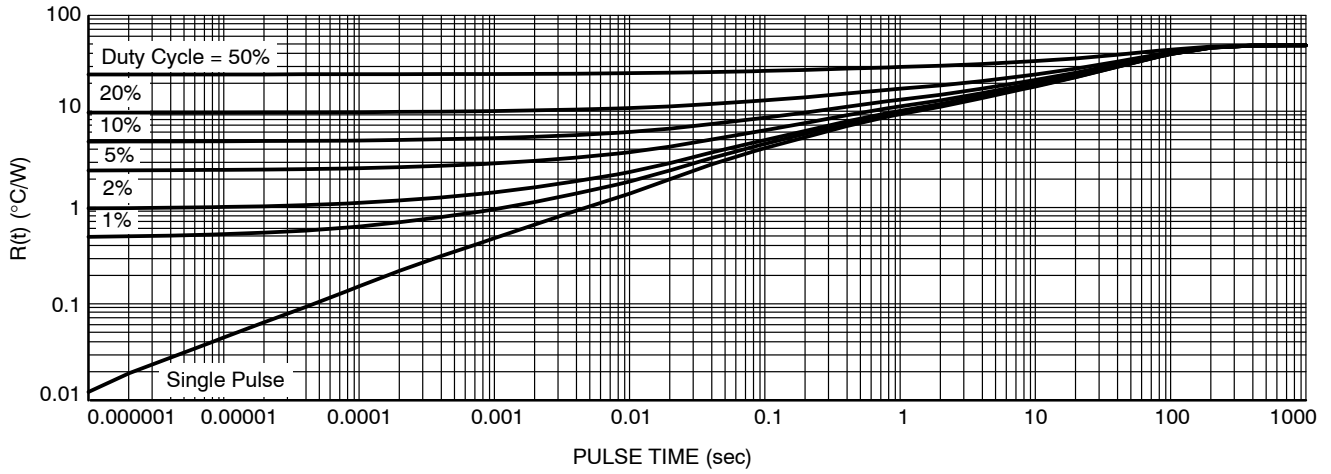


Figure 28. Thermal Response

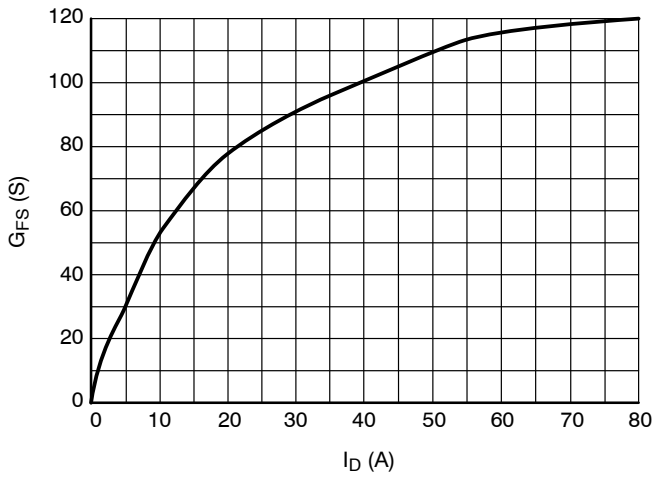


Figure 29.  $G_{FS}$  vs.  $I_D$

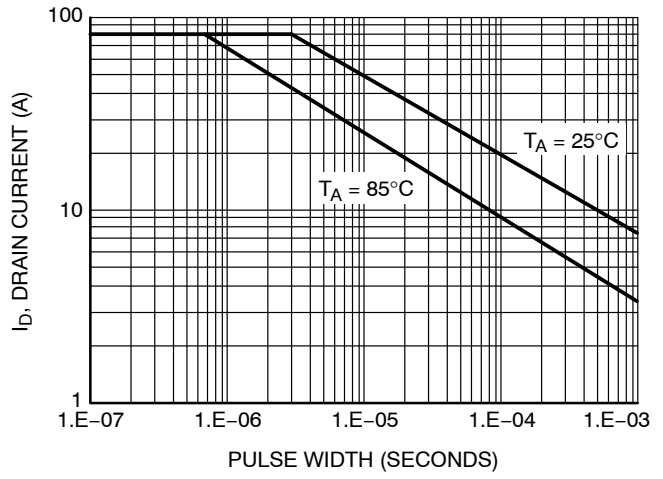
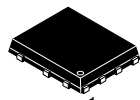


Figure 30. Avalanche Characteristics

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®

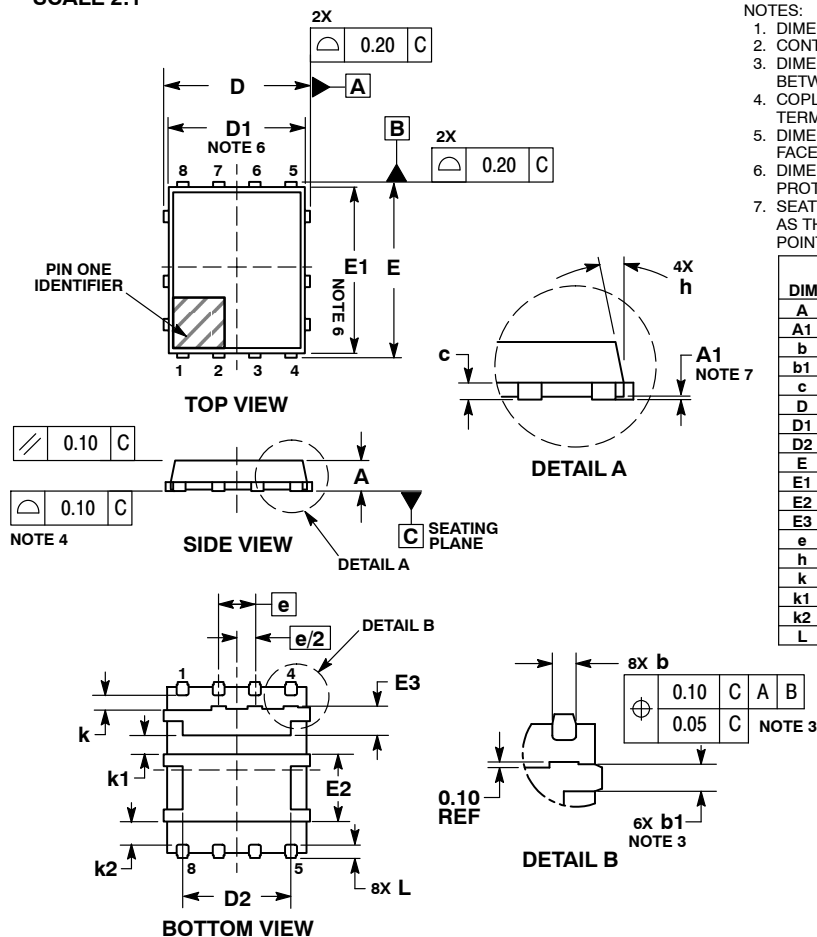


SCALE 2:1

### DFN8 5x6, 1.27P Dual Flag (SO8FL-Dual-Asymmetrical)

CASE 506BX  
ISSUE D

DATE 24 JUN 2014

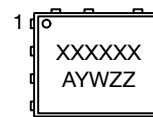


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
5. DIMENSIONS *b* AND *L* ARE MEASURED AT THE PACKAGE SURFACE.
6. DIMENSIONS *D1* AND *E1* DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
7. SEATING PLANE IS DEFINED BY THE TERMINALS. *A1* IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

MILLIMETERS		
DIM	MIN	MAX
A	0.90	1.10
A1	0.00	0.05
<i>b</i>	0.41	0.61
<i>b1</i>	0.41	0.61
<i>c</i>	0.23	0.33
D	5.00	5.30
D1	4.50	5.10
D2	3.50	4.22
E	6.00	6.30
E1	5.50	6.10
E2	2.27	2.67
E3	0.82	1.22
<i>e</i>	1.27 BSC	
<i>h</i>	---	12 °
<i>k</i>	0.39	0.59
<i>k1</i>	0.56	0.76
<i>k2</i>	0.73	0.93
<i>L</i>	0.35	0.55

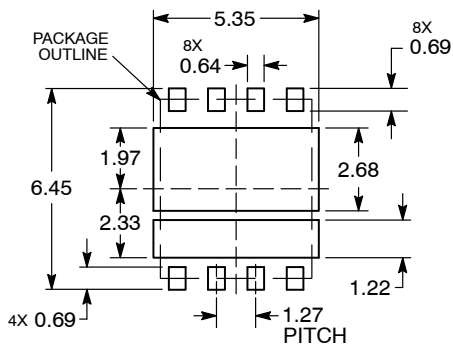
### GENERIC MARKING DIAGRAM\*



XXXXXX= Specific Device Code  
 A = Assembly Location  
 Y = Year  
 W = Work Week  
 ZZ = Lot Traceability

\*This information is generic. Please refer to device data sheet for actual part marking.

### RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSION: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLE 1:

- PIN 1. GATE 1  
 2. DRAIN 1  
 3. DRAIN 1  
 4. DRAIN 1  
 5. SOURCE 2  
 6. SOURCE 2  
 7. SOURCE 2  
 8. GATE 2  
 9. DRAIN 1  
 10. SOURCE 1/DRAIN 2

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